

UNISONIC TECHNOLOGIES CO., LTD

UF730-TD1 **Preliminary** Power MOSFET

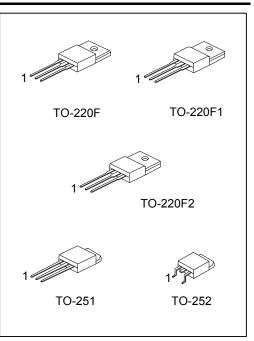
5.5A, 400V N-CHANNEL POWER MOSFET

DESCRIPTION

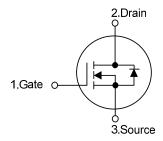
The UTC UF730-TD1 is a high voltage power MOSFET combines advanced trench MOSFET designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and high rugged avalanche characteristics. This power MOSFET is usually used in high speed switching applications of switching power supplies and adaptors.

FEATURES

- * $R_{DS(ON)} \le 1.2 \Omega @ V_{GS} = 10V, I_D = 3.0A$
- * Fast switching capability
- * Avalanche energy tested
- * Improved dv/dt capability, high ruggedness



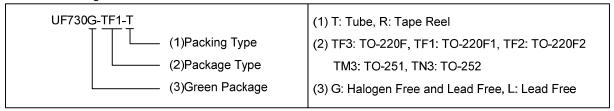
SYMBOL



ORDERING INFORMATION

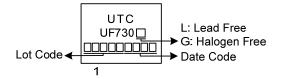
Ordering Number		Deelees	Pin Assignment			Da alsia a	
Lead Free	Halogen Free	Package	1	2	3	Packing	
UF730L-TF1-T	UF730G-TF1-T	TO-220F1	G	D	S	Tube	
UF730L-TF2-T	UF730G-TF2-T	TO-220F2	G	D	S	Tube	
UF730L-TF3-T	UF730G-TF3-T	TO-220F	G	D	S	Tube	
UF730L-TM3-T	UF730G-TM3-T	TO-251	G	D	S	Tube	
UF730L-TN3-R	UF730G-TN3-R	TO-252	G	D	S	Tape Reel	

Note: Pin Assignment: G: Gate D: Drain S: Source



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■ MARKING



■ ABSOLUTE MAXIMUM RATINGS (T_C=25°C, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		V_{DSS}	400	V
Gate-Source Voltage		V_{GSS}	±20	>
Continuous Drain Current		I_{D}	5.5	Α
Pulsed Drain Current (Note 2)		I_{DM}	11	Α
Avalanche Energy	Single Pulsed (Note 3)	E _{AS}	145.2	mJ
Peak Diode Recovery dv/c	It (Note 4)	dv/dt	3.6	V/ns
Power Dissipation	TO-220F/TO-220F1 TO-220F2	P_D	28	W
	TO-251/TO-252		46	W
Junction Temperature		TJ	+150	°C
Storage Temperature		T _{STG}	-55 ~ +150	°C

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.

- 2. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 3. L = 30mH, I_{AS} = 3.1A, V_{DD} = 50V, R_{G} = 25 Ω , Starting T_{J} = 25°C
- 4. $I_{SD} \le 5.5$ A, di/dt ≤ 200 A/ μ s, $V_{DD} \le BV_{DSS}$, Starting $T_J = 25$ °C

■ THERMAL DATA

PARAMETER		SYMBOL	RATING	UNIT
Junction to Ambient	TO-220F/TO-220F1 TO-220F2	θЈΑ	62.5	°C/W
	TO-251/TO-252		110	°C/W
Junction to Case	TO-220F/TO-220F1 TO-220F2	θЈС	4.4	°C/W
	TO-251/TO-252] [2.7 (Note)	°C/W

Note: Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

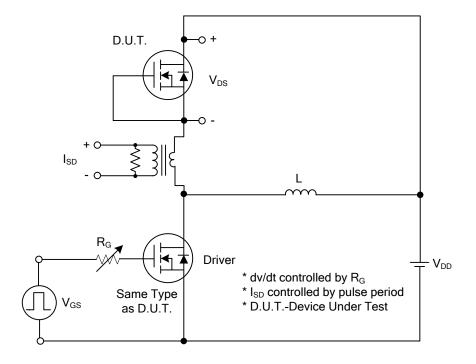
■ **ELECTRICAL CHARACTERISTICS** (T_J=25°C, unless otherwise specified)

PARAMETER		SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage		BV _{DSS}	V_{GS} =0V, I_{D} =250 μ A	400			V
Drain-Source Leakage Current		I_{DSS}	V _{DS} =400V, V _{GS} =0V			10	μΑ
Gate- Source Leakage Current	Forward		V_{GS} =20V, V_{DS} =0V			100	nA
	Reverse	I_{GSS}	V_{GS} =-20V, V_{DS} =0V			-100	nA
ON CHARACTERISTICS							
Gate Threshold Voltage		$V_{GS(TH)}$	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	2.0		4.0	V
Static Drain-Source On-State Resistance		R _{DS(ON)}	V _{GS} =10V, I _D =3.0A			1.2	Ω
DYNAMIC CHARACTERISTICS							
Input Capacitance		C _{ISS}	1/ -25\/ \/ -0\/		442		pF
Output Capacitance		Coss	V _{DS} =25V, V _{GS} =0V, -f=1.0MHz		59.2		pF
Reverse Transfer Capacitance		C_{RSS}	1-1.0IVII 12		3.9		pF
SWITCHING CHARACTERISTICS	S						
Total Gate Charge (Note 1)		Q_G	V_{DS} =320V, V_{GS} =10V,	=320V, V _{GS} =10V,			nC
Gate-Source Charge		Q_GS	I _D =5.5A, I _G =1mA		5.2		nC
Gate-Drain Charge		Q_GD	(Note 1, 2)		5.2		nC
Turn-On Delay Time (Note 1)		$t_{D(ON)}$	V _{DS} =100V, V _{GS} =10V,		7.2		ns
Turn-On Rise Time		t _R	I_{D} =5.5A, R_{G} =25 Ω		17.7		ns
Turn-Off Delay Time		t _{D(OFF)}	(Note 1, 2)		42.8		ns
Turn-Off Fall Time		t_{F}	(14010-1, 2)		26.5		ns
DRAIN-SOURCE DIODE CHARA	CTERISTICS	AND MAXIM	UM RATINGS				
Maximum Body-Diode Continuous Current		Is				5.5	Α
Maximum Body-Diode Pulsed Current		I_{SM}				11	Α
Drain-Source Diode Forward Voltage (Note 1)		V_{SD}	I _S =5.5A , V _{GS} =0V			1.4	V
Reverse Recovery Time (Note 1)		t _{rr}	I _S =5.5A , V _{GS} =0V		340		ns
Reverse Recovery Charge		Q_{rr}	di/dt=100A/μs 6.8		6.8		μC

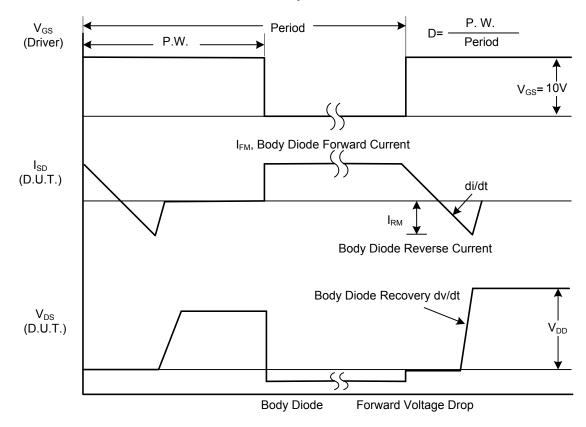
Notes: 1. Pulse Test: Pulse width ≤ 300µs, Duty cycle ≤ 2%.

^{2.} Essentially independent of operating temperature.

■ TEST CIRCUITS AND WAVEFORMS

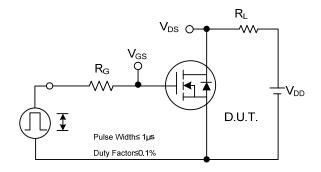


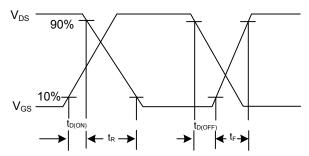
Peak Diode Recovery dv/dt Test Circuit



Peak Diode Recovery dv/dt Waveforms

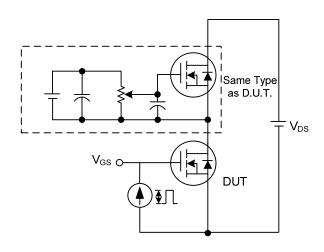
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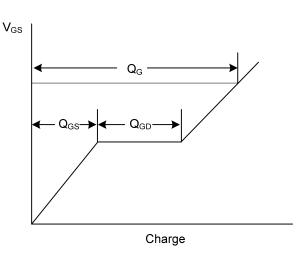




Switching Test Circuit

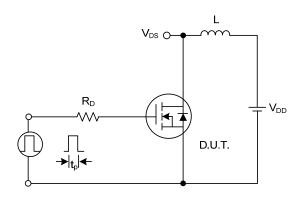
Switching Waveforms

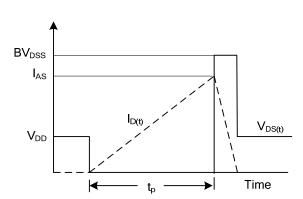




Gate Charge Test Circuit

Gate Charge Waveform





Unclamped Inductive Switching Test Circuit

Unclamped Inductive Switching Waveforms

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